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(54) **Title:** DISCRETE SEMICONDUCTOR DEVICE PACKAGE

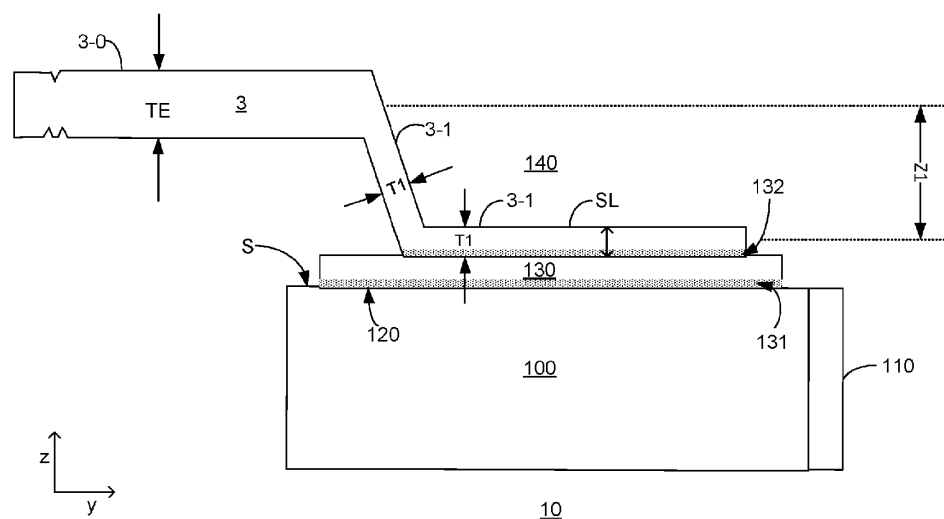


FIG. 1

(57) **Abstract:** A package (10) includes a semiconductor die (130) attached to a substrate (100) and a mold body (140) encapsulating the semiconductor die. A first portion of a lead (1-1, 2-1, 3-1) is directly bonded to a contact pad (SP, SSP, GP) on the semiconductor die with no intervening component between the first portion of the lead and the contact pad. A second portion of the lead extends outside the mold body to form an external terminal (1-0, 2-0, 3-0, 4-0, 5-0, 6-0, 7-0) of the package. The lead is a dual gauge lead with the first portion of the lead having a thickness perpendicular to the contact pad that is smaller than a thickness of the second portion of the lead extending outside the mold body.

[Continued on next page]

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